

Tflex UT20000 Series Ultra-Thin Thermal Gap Filler



Product Description

Tflex™ UT20000 is a specially formulated ultra-thin gap filler thermal interface material designed for thin interfaces that offers excellent thermal performance and high compliancy. It is designed without embedded reinforcing fiberglass to minimize contact resistance, yet still allows easy material handling and durability during assembly.

Tflex™ UT20000 provides excellent interfacing and its ability to wet out mating surfaces allows for efficient transfer of heat away from components. It is an ideal choice for low-pressure applications and optimum solution in handheld devices with thin interface gap and limited space requirements.

TflexTM UT20000 is electrically non-conductive, stable from -50°C thru 200°C and offered in thicknesses that range from 0.008" (200 μ m) up to 0.040" (1000 μ m).

FEATURES AND BENEFITS

- Thermal Conductivity of 3.0 W/mK
- No fiberglass carrier to minimize thermal resistance, yet still easy to handle
- Excellent surface wetting for low contact resistance
- Unique formulation minimizes thermal resistance at low mounting forces
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

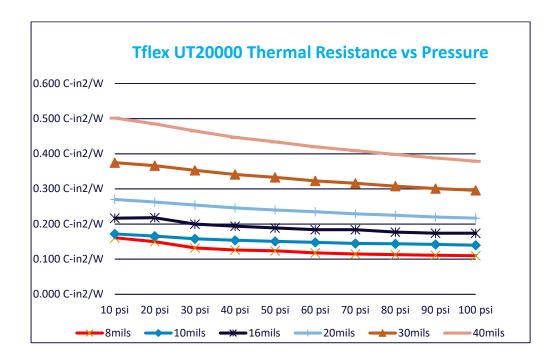
SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	200 μm (0.008")- 1000 μm (0.040")	N/A
Thermal Conductivity (W/mK)	3.0	Hot Disk
Density (g/cc)	3.2	Helium Pyncometer
Hardness (Shore 00)	83.3 (200-375) μm	ASTM D2240
	56.4 (400-1000) μm	
Outgassing TML (weight %)	0.34%	ASTM E595
Outgassing CVCM (weight %)	0.09%	ASTM E595
Temperature Range	-50°C to 200°C	Laird Test Method
Rth@ 200 μm, 10 psi, 50° C	0.25°C-in2/W	ASTM D5470
Dielectric Constant @ 1MHz	5.87	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	2.2 x 10 ^{^15} ohm-cm	ASTM D257

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AVAILABILITY

STANDARD THICKNESSES

- 0.008'' (200 μ m) up to 0.020'' (500 μ m) thick material available in 25 μ m increments
- Also available in 0.025" (625um), 0.030" (750 um), 0.035" (875um), 0.040" (1000 um)
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts. Custom die cut parts on a roll available for 200 μ m (0.008") thru 375 μ m (0.015")

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. UT20000 indicates Tflex UT20000 product line with thickness in microns



EXAMPLES:

- Tflex™ UT20200= 200 µm (0.008") thick Tflex™ UT20000 material
- Tflex™ UT20500= 500 µm (0.020") thick Tflex™ UT20000 material

A17759-00 Tflex UT20000 DS 051419



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